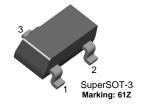


MMBF5434

N-Channel Switch

- · This device is designed for digital switching applications where very low on resistance is mandatory.
- Sourced from Process 58.



1. Drain 2. Source 3. Gate

Absolute Maximum Ratings * T_A=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{DG}	Drain-Gate Voltage	25	V
V_{GS}	Gate-Source Voltage	-25	V
I _{GF}	Forward Gate Current	10	mA
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics $T_A=25^{\circ}C$ unless otherwise noted

Parameter	Test Condition	Min.	Max.	Units
teristics		•		
Gate-Source Breakdwon Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$	-25		V
Gate Reverse Current	$V_{GS} = -15V, V_{DS} = 0$		200	nA
Gate-Source Cutoff Voltage	$V_{DS} = 5.0V, I_{D} = 3.0nA$	-1.0	-4.0	V
Drain Cutoff Voltag	V _{DS} = 5.0, V _{GS} = -10V		200	pА
teristics		•		
Zero-Gate Voltage Drain Current *	V _{DS} = 15V, I _{GS} = 0	30		mA
Drain-Source On Resistance	$V_{DS} = 0, I_{D} = 10 \text{mA}$		10	Ω
al Characteristics		•		
Input Capacitance	$V_{DS} = 0$, $V_{GS} = 10V$, $f = 1.0MHz$		30	pF
Reverse Transfer Capacitance	$V_{DS} = 0$, $V_{GS} = 10V$, $f = 1.0MHz$		15	pF
	deristics Gate-Source Breakdwon Voltage Gate Reverse Current Gate-Source Cutoff Voltage Drain Cutoff Voltag teristics Zero-Gate Voltage Drain Current * Drain-Source On Resistance al Characteristics Input Capacitance			

* Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

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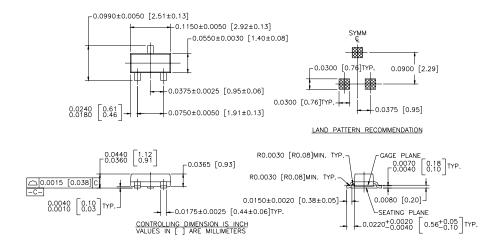
Thermal Characteristics T _A =25°C unless otherwise noted			
Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	556	°C/W

^{*} Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06"

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Package Dimensions

SuperSOT-3



Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench [®]	SuperSOT™-6
$CROSSVOLT^{TM}$	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS TM	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic [®]
E ² CMOS TM	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I ² C TM	OCX^{TM}	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET [®]
The Power Franc	hise™	OPTOLOGIC [®]	SILENT SWITCHER®	VCX^{TM}
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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